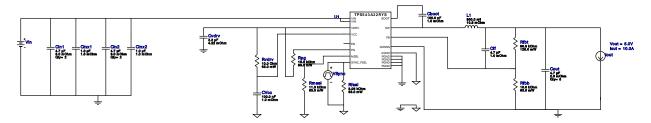


WEBENCH® Design Report

VinMin = 12.0V VinMax = 12.0V Vout = 5.0V Iout = 10.0A Device = TPS543A22RYS Topology = Buck Created = 2024-06-18 19:55:52.789 BOM Cost = \$4.59 BOM Count = 23 Total Pd = 3.54W

Design: 3 TPS543A22RYS TPS543A22RYS 12V-12V to 5.00V @ 10A



1.

Design Alerts

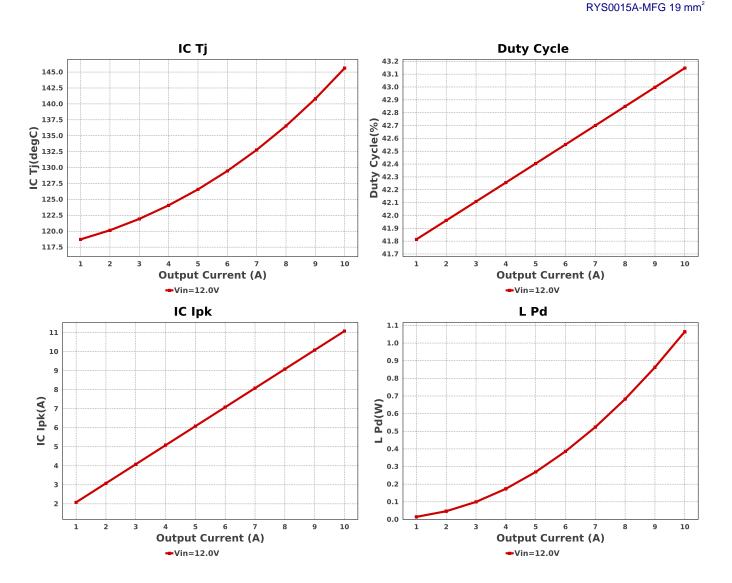
Component Selection Information

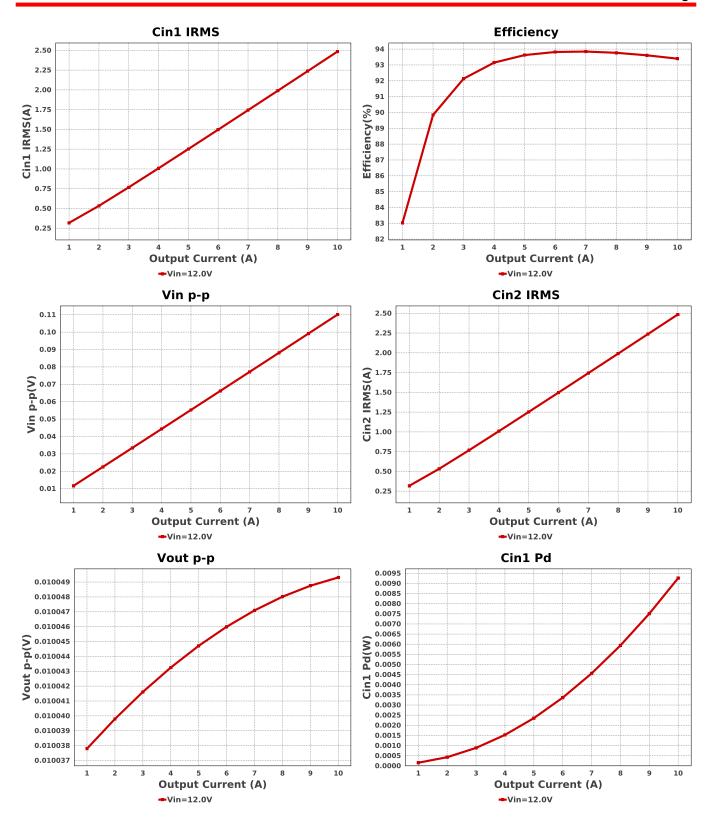
Please refer to the TPS543A22 datasheet for more information on synchronizing to an external clock.

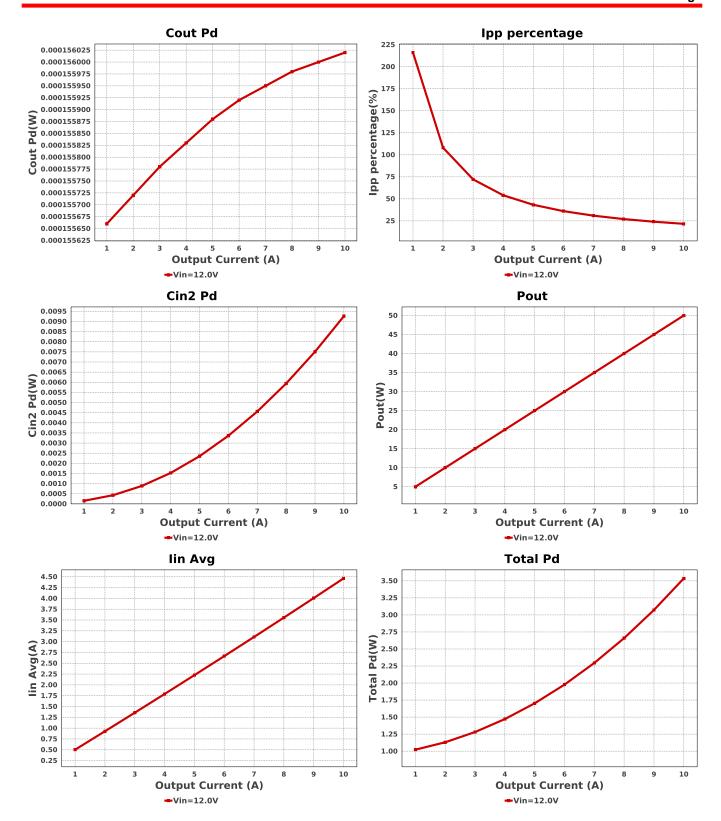
Electrical BOM

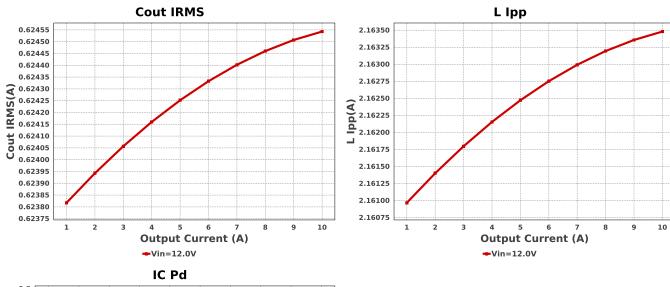
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
CVcc	MuRata	GRM155R71A104KA01D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm ²
Cboot	MuRata	GRM155R71A104KA01D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm ²
Cff	MuRata	GRM1555C1E4R7CA01D Series= C0G/NP0	Cap= 4.7 pF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm ²
Cin1	MuRata	GRM31CR71H475KA12L Series= X7R	Cap= 4.7 uF ESR= 3.0 mOhm VDC= 50.0 V IRMS= 4.98 A	2	\$0.10	1206 11 mm ²
Cin2	MuRata	GRM31CR71H475KA12L Series= X7R	Cap= 4.7 uF ESR= 3.0 mOhm VDC= 50.0 V IRMS= 4.98 A	2	\$0.10	1206 11 mm ²
Cinx1	Taiyo Yuden	TMK212B7105KG-T Series= X7R	Cap= 1.0 uF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	\$0.03	0805 7 mm ²
Cinx2	Taiyo Yuden	TMK212B7105KG-T Series= X7R	Cap= 1.0 uF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	\$0.03	0805 7 mm ²
Cout	MuRata	GRM21BR61E475MA12L Series= X5R	Cap= 4.7 uF ESR= 2.0 mOhm VDC= 25.0 V IRMS= 7.29 A	5	\$0.06	0805 7 mm ²
Cvdrv	MuRata	GRM21BR71A225KA01L Series= X7R	Cap= 2.2 uF ESR= 4.22 mOhm VDC= 10.0 V IRMS= 2.08454 A	1	\$0.03	0805 7 mm ²

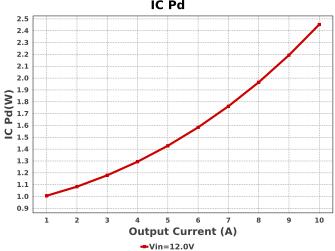
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
L1	Coilcraft	XAL6020-901MEB	L= 900.0 nH 10.6 mOhm	1	\$0.76	XAL6020 75 mm ²
Rfbb	Vishay-Dale	CRCW040210K0FKED Series= CRCWe3	Res= 10.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rfbt	Panasonic	ERJ-6ENF9092V Series= ERJ-6E	Res= 90.9 kOhm Power= 125.0 mW Tolerance= 1.0%	1	\$0.01	0805 7 mm ²
Rfsel	Vishay-Dale	CRCW04028K06FKED Series= CRCWe3	Res= 8.06 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rmsel	Vishay-Dale	CRCW040211K3FKED Series= CRCWe3	Res= 11.3 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rpg	Vishay-Dale	CRCW040210K0FKED Series= CRCWe3	Res= 10.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rvdrv	Vishay-Dale	CRCW040210R0FKED Series= CRCWe3	Res= 10.0 Ohm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
U1	Texas Instruments	TPS543A22RYS	Switcher	1	\$2.95	PVS0015A MEG 10 mm²











Operating Values

	3			
#	Name	Value	Category	Description
1.	Cin1 IRMS	2.485 A	Capacitor	Input capacitor RMS ripple current
2.	Cin1 Pd	9.262 mW	Capacitor	Input capacitor power dissipation
3.	Cin2 IRMS	2.485 A	Capacitor	Input capacitor RMS ripple current
4.	Cin2 Pd	9.262 mW	Capacitor	Input capacitor power dissipation
5.	Cout IRMS	624.543 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	156.02 μW	Capacitor	Output capacitor power dissipation
7.	Total Cin ESR	1.5 mOhm	Capacitor	Cin Capacitor ESR
8.	Total Cout ESR	400.0 μOhm	Capacitor	Cout Capacitor ESR
9.	Cramp	4.0 pF	IC .	Selected Cramp for setting Ramp amplitude
10.	IC lpk	11.082 A	IC	Peak switch current in IC
11.	IC Pd	2.453 W	IC	IC power dissipation
12.	IC Ti	145.62 degC	IC	IC junction temperature
13.	IC Tolerance	5.0 mV	IC	IC Feedback Tolerance
14.	ICThetaJA Effective	18.6 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
15.	lin Avg	4.461 A	IC	Average input current
16.	lpp percentage	21.635 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
17	L lpp	2.164 A	Inductor	Peak-to-peak inductor ripple current
	L Pd	1.064 W	Inductor	Inductor power dissipation
19.	L1 DCR	10.6 mOhm	Inductor	L1 DCR
20.	Cin1 Pd	9.262 mW	Power	Input capacitor power dissipation
21.		9.262 mW	Power	Input capacitor power dissipation
22.	Cout Pd	156.02 μW	Power	Output capacitor power dissipation
23.	IC Pd	2.453 W	Power	IC power dissipation
24.	L Pd	1.064 W	Power	Inductor power dissipation
25.	Total Pd	3.535 W	Power	Total Power Dissipation
26.	BOM Count	23	System	Total Design BOM count
-			Information	3
27.	Duty Cycle	43.147 %	System	Duty cycle
			Information	• •
28.	Efficiency	93.396 %	System	Steady state efficiency
	•		Information	•

#	Name	Value	Category	Description
29.	FootPrint	223.0 mm ²	System Information	Total Foot Print Area of BOM components
30.	Frequency	1.5 MHz	System Information	Switching frequency
31.	Inductor ripple current	30.0 %	System	Custom Inductor ripple current (% of average inductor current)
	requirement used for Inductor selection		Information	requirement used for Inductor selection
32.	lout	10.0 A	System Information	lout operating point
33.	lout transient step used	d 2.5 A	System	Custom Transient current step requirement that was used for Cout
	for Cout calculations		Information	selection (A).
34.	Mode	CCM	System Information	Conduction Mode
35.	Overshoot Value	31.294 mV	System Information	Theoretical Vout Overshoot Value
36.	Peak Over current Lim HS FET(Maximum)	it 18.38 A	System Information	Over current protection threshold
37.	Peak Over current Lim HS FET(Minimum)	it 16.63 A	System Information	Over current protection threshold
38.	Peak Over current Lim HS FET(typical)	it 17.5 A	System Information	Over current protection threshold
39.	Pout	50.0 W	System Information	Total output power
40.	Total BOM	\$4.59	System Information	Total BOM Cost
41.	Undershoot Value	76.442 mV	System Information	Theoretical Vout Undershoot Value
42.	Vin	12.0 V	System Information	Vin operating point
43.	Vin Ripple requirement used for Cin calculations	t 5.0 %	System Information	Custom maximum input ripple requirement that was used for Cin selection(% of Minimum Vin).
44.	Vin p-p	110.141 mV	System Information	Peak-to-peak input voltage
45.	Vout Actual	5.045 V	System Information	Vout Actual calculated based on selected voltage divider resistors
46.	Vout Ripple requirement used for Cout calculations	1.0 %	System Information	Custom maximum output ripple requirement that was used for Cout selection(% of Vout).
47.	Vout Tolerance	2.838 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
48.	Vout p-p	10.049 mV	System Information	Peak-to-peak output ripple voltage
49.	Vout transient requirement used for Cout calculations	4.0 %	System Information	Custom Transient voltage change requirement that was used for Cout selection (% of Vout).

Design Inputs

Name	Value	Description	
lout	10.0	Maximum Output Current	
VinMax	12.0	Maximum input voltage	
VinMin	12.0	Minimum input voltage	
Vout	5.0	Output Voltage	
base_pn	TPS543A22	Base Product Number	
source	DC	Input Source Type	
Та	100.0	Ambient temperature	
UserFsw	2.0	Customer Selected Frequency	

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

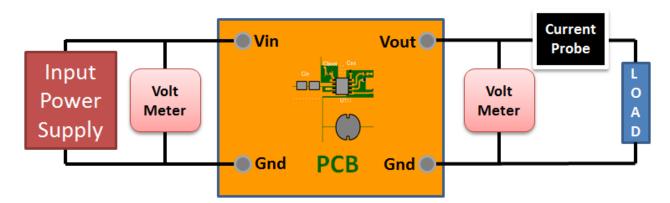
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 12.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

- 1. Master key: 2F58C85377208CF797727336275AA428[v1]
- 2. TPS543A22 Product Folder: http://www.ti.com/product/TPS543A22: contains the data sheet and other resources.

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